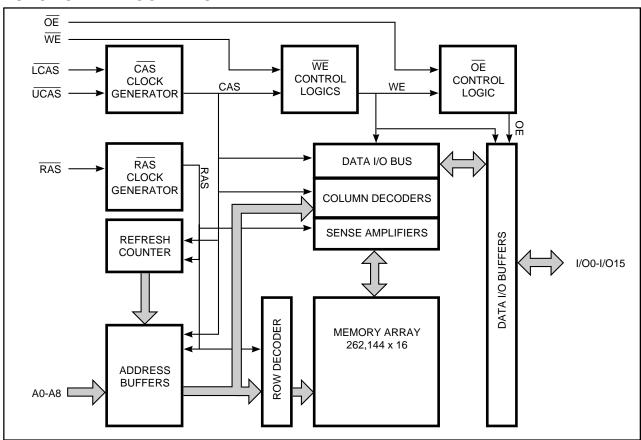
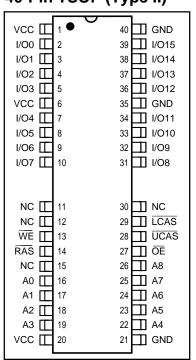


### **FUNCTIONAL BLOCK DIAGRAM**



### **PIN CONFIGURATIONS**

## 40-Pin TSOP (Type II)



### 40-Pin SOJ

	$\overline{}$	
vcc [	1 ●	40 GND
I/O0 [	2	39 🗍 1/O15
I/O1 [	3	38 🗍 1/O14
I/O2 [	4	37 🗍 1/013
I/O3 [	5	36 I/O12
vcc [	6	35 🛮 GND
I/O4 [	7	34 🗍 1/011
I/O5 [	8	33 🔲 I/O10
I/O6 [	9	32 🗍 1/09
I/O7 [	10	31 🔲 1/08
NC [	11	30 🛘 NC
NC [	12	29 🔲 LCAS
WE	13	28 UCAS
RAS [	14	27 🗍 ŌĒ
NC [	15	26 🔲 A8
A0 [	16	25 🛮 A7
A1 [	17	24 🗍 A6
A2 [	18	23 🗍 A5
A3 [	19	22 🗍 A4
VCC [	20	21 GND
	<u> </u>	
	·	·

### PIN DESCRIPTIONS

A0-A8	Address Inputs
I/O0-I/O15	Data Inputs/Outputs
WE	Write Enable
ŌĒ	Output Enable
RAS	Row Address Strobe
UCAS	Upper Column Address Strobe
<u>LCAS</u>	Lower Column Address Strobe
Vcc	Power
GND	Ground
NC	No Connection



### **TRUTH TABLE**

Function	RAS	LCAS	UCAS	WE	ŌĒ	Address tr/tc	I/O
Standby	Н	Н	Н	Χ	Χ	Χ	High-Z
Read: Word	L	L	L	Н	L	ROW/COL	Dout
Read: Lower Byte	L	L	Н	Н	L	ROW/COL	Lower Byte, Dout Upper Byte, High-Z
Read: Upper Byte	L	Н	L	Н	L	ROW/COL	Lower Byte, High-Z Upper Byte, Dout
Write: Word (Early Write)	L	L	L	L	Χ	ROW/COL	DIN
Write: Lower Byte (Early Write)	) L	L	Н	L	Х	ROW/COL	Lower Byte, DIN Upper Byte, High-Z
Write: Upper Byte (Early Write)	) L	Н	L	L	Х	ROW/COL	Lower Byte, High-Z Upper Byte, DIN
Read-Write <sup>(1,2)</sup>	L	L	L	$H{ ightarrow} L$	L→H	ROW/COL	Dout, Din
Hidden Refresh <sup>2)</sup>	Read $L\rightarrow H\rightarrow L$	L	L	Н	L	ROW/COL	Dout
	Write $L\rightarrow H\rightarrow L$	L	L	L	Χ	ROW/COL	Douт
RAS-Only Refresh	L	Н	Н	Χ	Χ	ROW/NA	High-Z
CBR Refresh <sup>(3)</sup>	H→L	L	L	Х	Х	Х	High-Z

- These WRITE cycles may also be BYTE WRITE cycles (either LCAS or UCAS active).
   These READ cycles may also be BYTE READ cycles (either LCAS or UCAS active).
   At least one of the two CAS signals must be active (LCAS or UCAS).



### **FUNCTIONAL DESCRIPTION**

The IS41C16257 and the IS41LV16257 are CMOS DRAMs optimized for high-speed bandwidth, low-power applications. During READ or WRITE cycles, each bit is uniquely addressed through the 18 address bits. These are entered nine bits (A0-A8) at a time. The row address is latched by the Row Address Strobe (RAS). The column address is latched by the Column Address Strobe (CAS). RAS is used to latch the first nine bits and CAS is used to latch the latter nine bits.

The IS41C16257 and the IS41LV16257 has two  $\overline{CAS}$  controls,  $\overline{LCAS}$  and  $\overline{UCAS}$ . The  $\overline{LCAS}$  and  $\overline{UCAS}$  inputs internally generate a  $\overline{CAS}$  signal functioning in an identical manner to the single  $\overline{CAS}$  input on the other 256K x 16 DRAMs. The key difference is that each  $\overline{CAS}$  controls its corresponding I/O tristate logic (in conjunction with  $\overline{OE}$  and  $\overline{WE}$  and  $\overline{RAS}$ ).  $\overline{LCAS}$  controls I/O0 - I/O7 and  $\overline{UCAS}$  controls I/O8 - I/O15.

The IS41C16257 and the IS41LV16257  $\overline{\text{CAS}}$  function is determined by the first  $\overline{\text{CAS}}$  ( $\overline{\text{LCAS}}$  or  $\overline{\text{UCAS}}$ ) transitioning LOW and the last transitioning back HIGH. The two  $\overline{\text{CAS}}$  controls give the IS41C16257 both BYTE READ and BYTE WRITE cycle capabilities.

### **Memory Cycle**

A memory cycle is initiated by bringing  $\overline{RAS}$  LOW and it is terminated by returning both  $\overline{RAS}$  and  $\overline{CAS}$  HIGH. To ensure proper device operation and data integrity any memory cycle, once initiated, must not be ended or aborted before the minimum tras time has expired. A new cycle must not be initiated until the minimum precharge time transfer has elapsed.

## **Read Cycle**

A read cycle is initiated by the falling edge of  $\overline{CAS}$  or  $\overline{OE}$ , whichever occurs last, while holding  $\overline{WE}$  HIGH. The column address must be held for a minimum time specified by tar. Data Out becomes valid only when trac, taa, toac and toea are all satisfied. As a result, the access time is dependent

on the timing relationships between these parameters.

## **Write Cycle**

A write cycle is initiated by the falling edge of  $\overline{CAS}$  and  $\overline{WE}$ , whichever occurs last. The input data must be valid at or before the falling edge of  $\overline{CAS}$  or  $\overline{WE}$ , whichever occurs last.

## **Refresh Cycle**

To retain data, 512 refresh cycles are required in each 8 ms period. There are two ways to refresh the memory:

- By clocking each of the 512 row addresses (A0 through A8) with RAS at least once every 8 ms. Any read, write, read-modify-write or RAS-only cycle refreshes the addressed row.
- Using a CAS-before-RAS refresh cycle. CAS-before-RAS refresh is activated by the falling edge of RAS, while holding CAS LOW. In CAS-before-RAS refresh cycle, an internal 9-bit counter provides the row addresses and the external address inputs are ignored.

CAS-before-RAS is a refresh-only mode and no data access or device selection is allowed. Thus, the output remains in the High-Z state during the cycle.

### Power-On

After application of the Vcc supply, an initial pause of  $200\,\mu s$  is required followed by a minimum of eight initialization cycles (any combination of cycles containing a  $\overline{RAS}$  signal).

During power-on, it is recommended that RAS track with Vcc or be held at a valid ViH to avoid current surges.



### ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Parameters		Rating	Unit
VT	Voltage on Any Pin Relative to GND	5V	-1.0 to +7.0	V
		3.3V	-0.5 t0 +4.6	
Vcc	Supply Voltage	5V	-1.0 to +7.0	V
		3.3V	-0.5 t0 +4.6	
Іоит	Output Current		50	mA
PD	Power Dissipation		1	W
TA	Operation Temperature	Com.	0 to 70	°C
		Ind.	-40 to +85	
Тѕтс	Storage Temperature		-55 to +125	°C

#### Note:

## **RECOMMENDED OPERATING CONDITIONS** (Voltages are referenced to GND)

Symbol	Parameter	Voltage	Min.	Тур.	Max.	Unit
Vcc	Supply Voltage	5V	4.5	5.0	5.5	V
Vcc	Supply Voltage	3.3V	3.0	3.3	3.6	V
ViH	Input High Voltage	5V	2.4	_	Vcc + 1.0	V
VIH	Input High Voltage	3.3V	2.0	_	Vcc + 0.3	V
VIL	Input Low Voltage	5V	-1.0	_	0.8	V
VIL	Input Low Voltage	3.3	-0.3	_	0.8	V
TA	Ambient Temperature	Com.	0	_	70	°C
		Ind.	-40	_	85	

### CAPACITANCE(1,2)

Symbol	Parameter	Max.	Unit
CIN1	Input Capacitance: A0-A8	5	pF
CIN2	Input Capacitance: RAS, UCAS, LCAS, WE, OE	7	pF
Сю	Data Input/Output Capacitance: I/O0-I/O15	7	pF

- 1. Tested initially and after any design or process changes that may affect these parameters.
- 2. Test conditions: T<sub>A</sub> = 25°C, f = 1 MHz,  $Vcc = 5.0V \pm 10\%$  or  $Vcc=3.3V \pm 10\%$ .

Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause
permanent damage to the device. This is a stress rating only and functional operation of the
device at these or any other conditions above those indicated in the operational sections of
this specification is not implied. Exposure to absolute maximum rating conditions for
extended periods may affect reliability.



## **ELECTRICAL CHARACTERISTICS**(1) (Recommended Operation Conditions unless otherwise noted.)

Symbol	Parameter	<b>Test Condition</b>		Speed	Min.	Max.	Unit
lı∟	Input Leakage Current	Any input $0V \le VIN \le VCC$ Other inputs not under test = $0V$			-10	10	μΑ
lio	Output Leakage Current	Output is disabled (Hi-Z) 0V ≤ Vouт ≤ Vcc			-10	10	μΑ
Vон	Output High Voltage Level	lон = −2.5 mA			2.4	_	V
Vol	Output Low Voltage Level	IoL = 2.1 mA			_	0.4	V
lcc1	Stand-by Current: TTL	RAS, LCAS, UCAS ≥ VIH	Com. Ind.	5V 5V	_	2 3	mA
lcc1	Stand-by Current: TTL	RAS, LCAS, UCAS ≥ VIH	Com. Ind.		_	1 2	mA
lcc2	Stand-by Current: CMOS	RAS, LCAS, UCAS ≥ Vcc - 0.2V		5V	_	2	mA
Icc2	Stand-by Current: CMOS	RAS, LCAS, UCAS ≥ Vcc - 0.2V		3.3V	_	1	mA
Icc3	Operating Current: Random Read/Write <sup>(2,3,4)</sup> Average Power Supply Current	RAS, LCAS, UCAS, Address Cycling, trc = trc (min.)		-35 -60	_	230 170	mA
Icc4	Operating Current: Fast Page Mode <sup>(2,3,4)</sup> Average Power Supply Current	RAS = VIL, LCAS, UCAS, Cycling tpc = tpc (min.)		-35 -60	_	220 160	mA
Icc5	Refresh Current: RAS-Only <sup>(2,3)</sup> Average Power Supply Current	RAS Cycling, $\overline{LCAS}$ , $\overline{UCAS} \ge V_{IH}$ trc = trc (min.)		-35 -60	_	230 170	mA
Icc6	Refresh Current: CBR <sup>(2,3,5)</sup> Average Power Supply Current	RAS, LCAS, UCAS Cycling trc = trc (min.)		-35 -60	_	230 170	mA

<sup>1.</sup> An initial pause of 200  $\mu$ s is required after power-up followed by eight  $\overline{RAS}$  refresh cycles ( $\overline{RAS}$ -Only or CBR) before proper device operation is assured. The eight  $\overline{RAS}$  cycles wake-up should be repeated any time the tree refresh requirement is exceeded.

<sup>2.</sup> Dependent on cycle rates.

<sup>3.</sup> Specified values are obtained with minimum cycle time and the output open.

<sup>4.</sup> Column-address is changed once each fast page cycle.

<sup>5.</sup> Enables on-chip refresh and address counters.



# AC CHARACTERISTICS(1,2,3,4,5,6) (Recommended Operating Conditions unless otherwise noted.)

		-3	5	-6	60	
Symbol	Parameter	Min.	Max.	Min.	Max.	Units
trc	Random READ or WRITE Cycle Time	60	_	110	_	ns
trac	Access Time from RAS(6, 7)	_	35	_	60	ns
tcac	Access Time from CAS(6, 8, 15)	_	10	_	15	ns
<b>t</b> AA	Access Time from Column-Address <sup>(6)</sup>	_	18	_	30	ns
tras	RAS Pulse Width	35	10K	60	10K	ns
<b>t</b> RP	RAS Precharge Time	20	_	40	_	ns
tcas	CAS Pulse Width(26)	6	10K	10	10K	ns
tcp	CAS Precharge Time <sup>(9, 25)</sup>	5	_	10	_	ns
tcsн	CAS Hold Time (21)	35	_	60	_	ns
trcd	RAS to CAS Delay Time(10, 20)	11	28	20	45	ns
tasr	Row-Address Setup Time	0	_	_ (	)	— ns
<b>t</b> rah	Row-Address Hold Time	6	_	10	_	ns
tasc	Column-Address Setup Time(20)	0		0		ns
tcah	Column-Address Hold Time <sup>(20)</sup>	6	_	10		ns
tar	Column-Address Hold Time (referenced to RAS)	30	_	40	_	ns
trad	RAS to Column-Address Delay Time(11)	12	20	15	30	ns
tral	Column-Address to RAS Lead Time	18	_	30	_	ns
trpc	RAS to CAS Precharge Time	0	_	0	_	ns
trsh	RAS Hold Time <sup>(27)</sup>	8	_	15	_	ns
tclz	CAS to Output in Low-Z(15, 29)	3	_	3	_	ns
tcrp	CAS to RAS Precharge Time(21)	5	_	5	_	ns
top	Output Disable Time(19, 28, 29)	3	15	3	15	ns
toe	Output Enable Time(15, 16)	_	10	_	15	ns
toehc	OE HIGH Hold Time from CAS HIGH	10	_	10	_	ns
toep	OE HIGH Pulse Width	10	_	10	_	ns
toes	OE LOW to CAS HIGH Setup Time	5	_	5		ns
trcs	Read Command Setup Time <sup>(17, 20)</sup>	0	_	0	_	ns
trrh	Read Command Hold Time (referenced to RAS) <sup>(12)</sup>	0	_	0	_	ns
trch	Read Command Hold Time (referenced to CAS)(12, 17, 21)	0	_	0	_	ns
twcн	Write Command Hold Time(17, 27)	5	_	10	_	ns
twcr	Write Command Hold Time (referenced to RAS)(17)	30	_	50	_	ns
twp	Write Command Pulse Width(17)	5	_	10	_	ns
twpz	WE Pulse Widths to Disable Outputs	10	_	10	_	ns
<b>t</b> RWL	Write Command to RAS Lead Time(17)	8	_	15		ns
tcwl	Write Command to CAS Lead Time(17, 21)	8	_	15		ns
twcs	Write Command Setup Time(14, 17, 20)	0	_	0		ns
tohr	Data-in Hold Time (referenced to RAS)	30		40	_	ns

(Continued)



# **AC CHARACTERISTICS**(1,2,3,4,5,6) (Recommended Operating Conditions unless otherwise noted.)

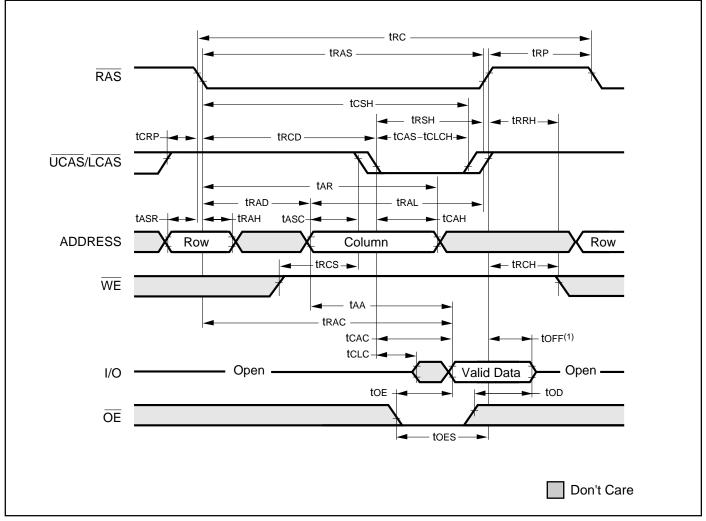
		-:	35	-(	60	
Symbol	Parameter	Min.	Max.	Min.	Max.	Units
tach	Column-Address Setup Time to CAS Precharge during WRITE Cycle	15	_	15	_	ns
<b>t</b> OEH	OE Hold Time from WE during READ-MODIFY-WRITE cycle(18)	8	_	15	_	ns
tos	Data-In Setup Time(15, 22)	0	_	0	_	ns
tрн	Data-In Hold Time(15, 22)	6	_	10	_	ns
trwc	READ-MODIFY-WRITE Cycle Time	80	_	140	_	ns
trwd	RAS to WE Delay Time during READ-MODIFY-WRITE Cycle <sup>(14)</sup>	45	_	80	_	ns
tcwd	CAS to WE Delay Time(14, 20)	25	_	36	_	ns
tawd	Column-Address to WE Delay Time(14)	30	_	49	_	ns
tpc	Fast Page Mode READ or WRITE Cycle Time <sup>(24)</sup>	12	_	25	_	ns
trasp	RAS Pulse Width	35	100K	60	100K	ns
<b>t</b> CPA	Access Time from CAS Precharge(15)	_	21	_	34	ns
<b>t</b> PRWC	READ-WRITE Cycle Time(24)	40	_	56	_	ns
toff	Output Buffer Turn-Off Delay from CAS or RAS(13,15,19,29)	3	15	3	15	ns
twnz	Output Disable Delay from WE	3	15	3	15	ns
tclch	Last CAS going LOW to First CAS returning HIGH <sup>(23)</sup>	10	_	10	_	ns
tcsr	CAS Setup Time (CBR REFRESH)(30, 20)	8	_	10	_	ns
tchr	CAS Hold Time (CBR REFRESH)(30, 21)	8	_	10	_	ns
tord	OE Setup Time prior to RAS during HIDDEN REFRESH Cycle	0	_	0	_	ns
tref	Refresh Period (512 Cycles)	_	8	_	8	ms
tτ	Transition Time (Rise or Fall)(2, 3)	1	50	1	50	ns



- 1. An initial pause of 200 μs is required after power-up followed by eight RAS refresh cycle (RAS-Only or CBR) before proper device operation is assured. The eight RAS cycles wake-up should be repeated any time the tree refresh requirement is exceeded.
- 2. Viн (MIN) and Vi∟ (MAX) are reference levels for measuring timing of input signals. Transition times, are measured between Vi⊣ and Vi∟ (or between Vi∟ and Vi⊢) and assume to be 1 ns for all inputs.
- 3. In addition to meeting the transition rate specification, all input signals must transit between V<sub>IH</sub> and V<sub>IL</sub> (or between V<sub>IL</sub> and V<sub>IH</sub>) in a monotonic manner.
- 4. If  $\overline{CAS}$  and  $\overline{RAS} = V_{IH}$ , data output is High-Z.
- 5. If  $\overline{CAS} = V_{IL}$ , data output may contain data from the last valid READ cycle.
- 6. Measured with a load equivalent to one TTL gate and 50 pF.
- Assumes that tRCD ≤ tRCD (MAX). If tRCD is greater than the maximum recommended value shown in this table, tRAC will increase by the amount that tRCD exceeds the value shown.
- 8. Assumes that  $trcd \ge trcd$  (MAX).
- 9. If CAS is LOW at the falling edge of RAS, data out will be maintained from the previous cycle. To initiate a new cycle and clear the data output buffer, CAS and RAS must be pulsed for tcp.
- 10. Operation with the tRCD (MAX) limit ensures that tRAC (MAX) can be met. tRCD (MAX) is specified as a reference point only; if tRCD is greater than the specified tRCD (MAX) limit, access time is controlled exclusively by tCAC.
- 11. Operation within the trad (MAX) limit ensures that trad (MAX) can be met. trad (MAX) is specified as a reference point only; if trad is greater than the specified trad (MAX) limit, access time is controlled exclusively by trad.
- 12. Either trch or trrh must be satisfied for a READ cycle.
- 13. toff (MAX) defines the time at which the output achieves the open circuit condition; it is not a reference to Voh or Vol.
- 14. twcs, trwb, tawb and tcwb are restrictive operating parameters in LATE WRITE and READ-MODIFY-WRITE cycle only. If twcs ≥ twcs (MIN), the cycle is an EARLY WRITE cycle and the data output will remain open circuit throughout the entire cycle. If trwb ≥ trwb (MIN), tawb ≥ tawb (MIN) and tcwb ≥ tcwb (MIN), the cycle is a READ-WRITE cycle and the data output will contain data read from the selected cell. If neither of the above conditions is met, the state of I/O (at access time and until CAS and RAS or OE go back to Vih) is indeterminate. OE held HIGH and WE taken LOW after CAS goes LOW result in a LATE WRITE (OE-controlled) cycle.
- 15. Output parameter (I/O) is referenced to corresponding CAS input, I/O0-I/O7 by LCAS and I/O8-I/O15 by UCAS.
- 16. During a READ cycle, if  $\overline{OE}$  is LOW then taken HIGH before  $\overline{CAS}$  goes HIGH, I/O goes open. If  $\overline{OE}$  is tied permanently LOW, a LATE WRITE or READ-MODIFY-WRITE is not possible.
- 17. Write command is defined as WE going low.
- 18. LATE WRITE and READ-MODIFY-WRITE cycles must have both too and toen met (OE HIGH during WRITE cycle) in order to ensure that the output buffers will be open during the WRITE cycle. The I/Os will provide the previously written data if CAS remains LOW and OE is taken back to LOW after toen is met.
- 19. The I/Os are in open during READ cycles once top or toff occur.
- 20. The first  $\chi \overline{\text{CAS}}$  edge to transition LOW.
- 21. The last  $\chi \overline{\text{CAS}}$  edge to transition HIGH.
- 22. These parameters are referenced to CAS leading edge in EARLY WRITE cycles and WE leading edge in LATE WRITE or READ-MODIFY-WRITE cycles.
- 23. Last falling  $\chi \overline{CAS}$  edge to first rising  $\chi \overline{CAS}$  edge.
- 24. Last rising  $\chi \overline{CAS}$  edge to next cycle's last rising  $\chi \overline{CAS}$  edge.
- 25. Last rising  $\chi \overline{CAS}$  edge to first falling  $\chi \overline{CAS}$  edge.
- 26. Each χCAS must meet minimum pulse width.
- 27. Last  $\chi \overline{CAS}$  to go LOW.
- 28. I/Os controlled, regardless UCAS and LCAS.
- 29. The 3 ns minimum is a parameter guaranteed by design.
- 30. Enables on-chip refresh and address counters.



## **FAST-PAGE-MODE READ CYCLE**

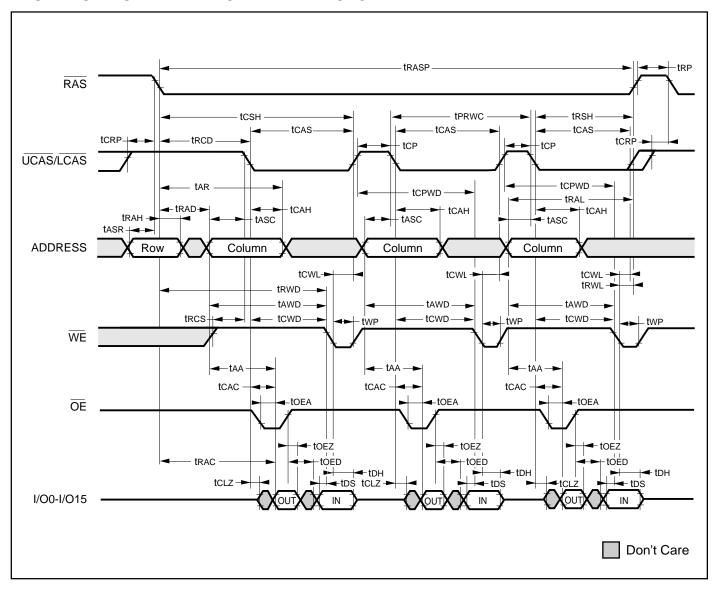


### Note:

1. toff is referenced from rising edge of  $\overline{\text{CAS}}$ .

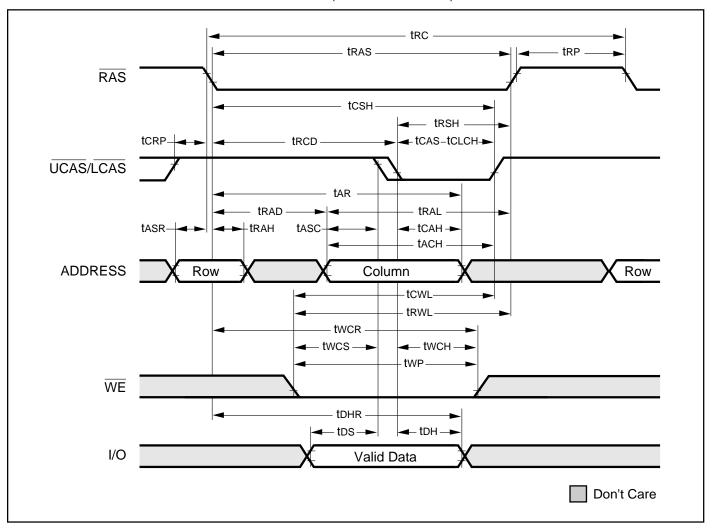


### FAST PAGE MODE READ-MODIFY-WRITE CYCLE



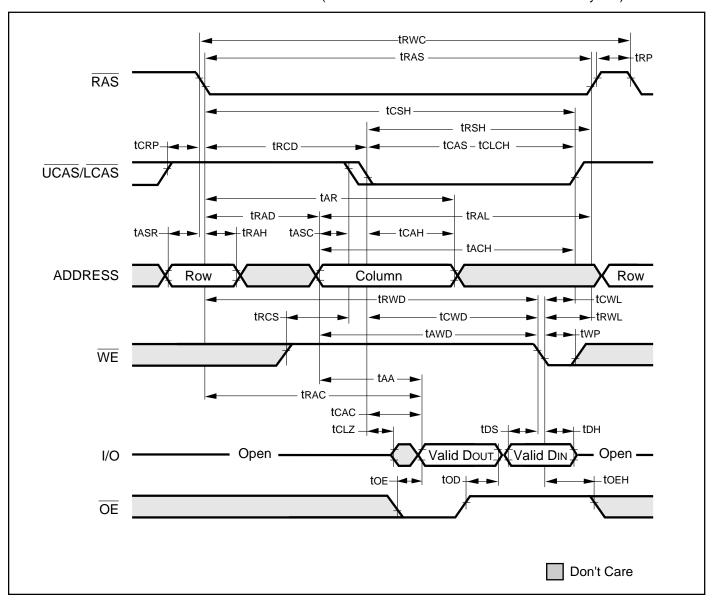


# FAST-PAGE-MODE EARLY WRITE CYCLE (OE = DON'T CARE)



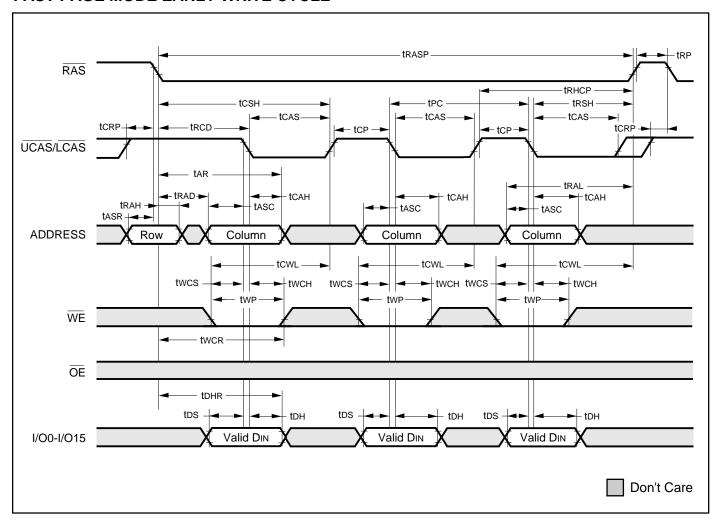


## FAST-PAGE-MODE READ WRITE CYCLE (LATE WRITE and READ-MODIFY-WRITE Cycles)





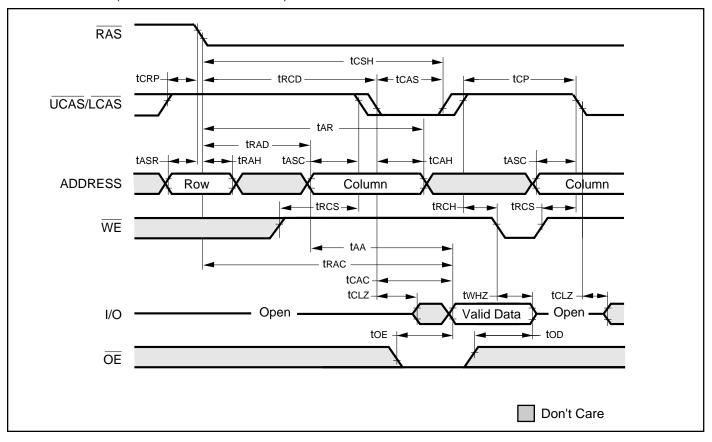
## **FAST PAGE MODE EARLY WRITE CYCLE**



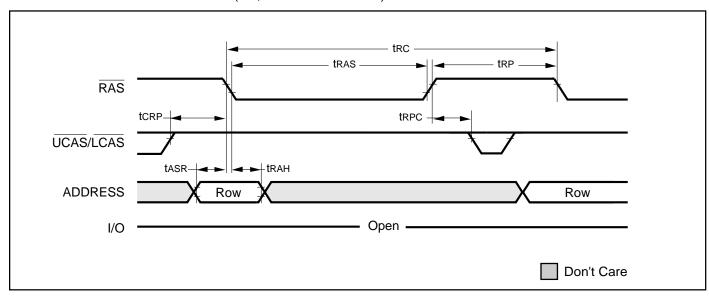


### **AC WAVEFORMS**

## READ CYCLE (With WE-Controlled Disable)

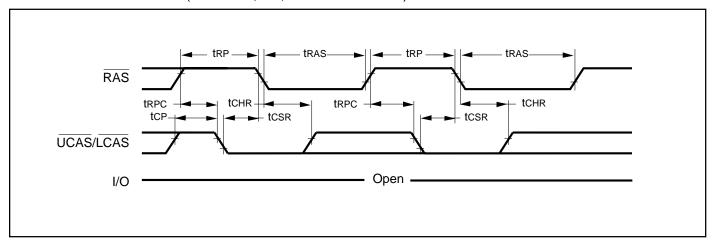


# RAS-ONLY REFRESH CYCLE (OE, WE = DON'T CARE)

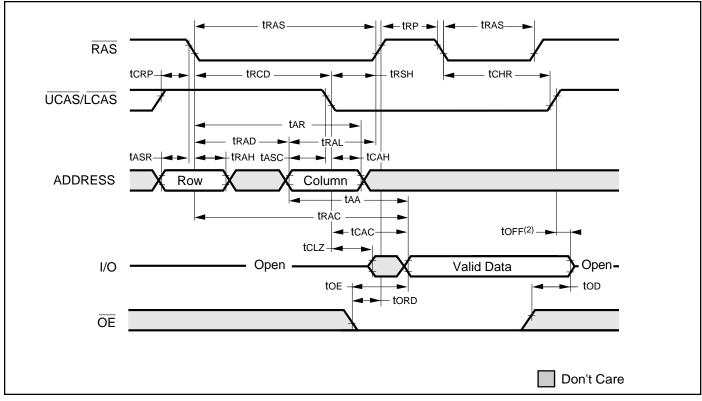




# $\overline{\textbf{CBR}}$ REFRESH CYCLE (Addresses; $\overline{\textbf{WE}}$ , $\overline{\textbf{OE}}$ = DON'T CARE)



## HIDDEN REFRESH CYCLE(1) (WE = HIGH; OE = LOW)



- 1. A Hidden Refresh may also be perfor<u>med</u> aft<u>er a Write Cycle</u>. In this case,  $\overline{\text{WE}}$  = LOW and  $\overline{\text{OE}}$  = HIGH.
- 2. toff is referenced from rising edge of RAS or CAS, whichever occurs last.



# ORDERING INFORMATION IS41C16257

Commercial Range: 0°C to 70°C

Speed (ns)	peed (ns) Order Part No. Package	
35	IS41C16257-35K IS41C16257-35T	400-mil SOJ
60	IS41C16257-551	400-mil TSOP (Type II) 400-mil SOJ
	IS41C16257-60T	400-mil TSOP (Type II)

# ORDERING INFORMATION IS41LV16257

Commercial Range: 0°C to 70°C

Speed (ns)	Order Part No.	Package
35	IS41LV16257-35K	400-mil SOJ
	IS41LV16257-35T	400-mil TSOP (Type II)
60	IS41LV16257-60K	400-mil SOJ
	IS41LV16257-60T	400-mil TSOP (Type II)

## Industrial Range: -40°C to 85°C

Speed (ns)	Order Part No.	Package
35	IS41C16257-35KI	400-mil SOJ
	IS41C16257-35TI	400-mil TSOP (Type II)
60	IS41C16257-60KI	400-mil SOJ
	IS41C16257-60TI	400-mil TSOP (Type II)

## Industrial Range: -40°C to 85°C

Speed (ns)	Order Part No.	Package
35	IS41LV16257-35KI	400-mil SOJ
	IS41LV16257-35TI	400-mil TSOP (Type II)
60	IS41LV16257-60KI	400-mil SOJ
	IS41LV16257-60TI	400-mil TSOP (Type II)



# Integrated Silicon Solution, Inc.

2231 Lawson Lane Santa Clara, CA 95054 Tel: 1-800-379-4774 Fax: (408) 588-0806

E-mail: sales@issi.com

www.issi.com